

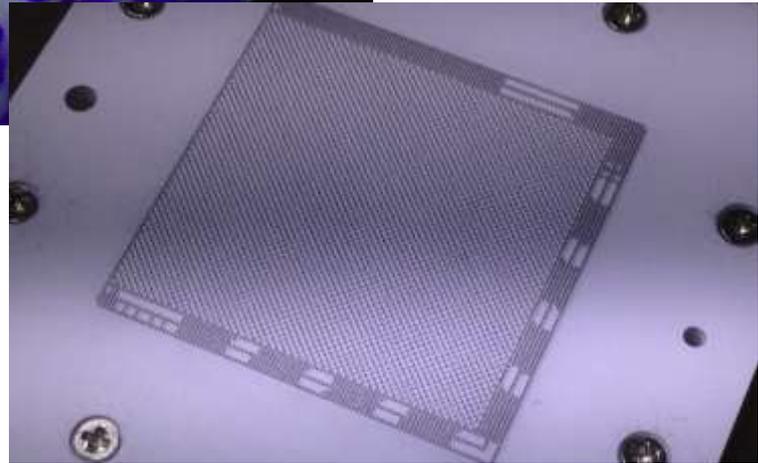
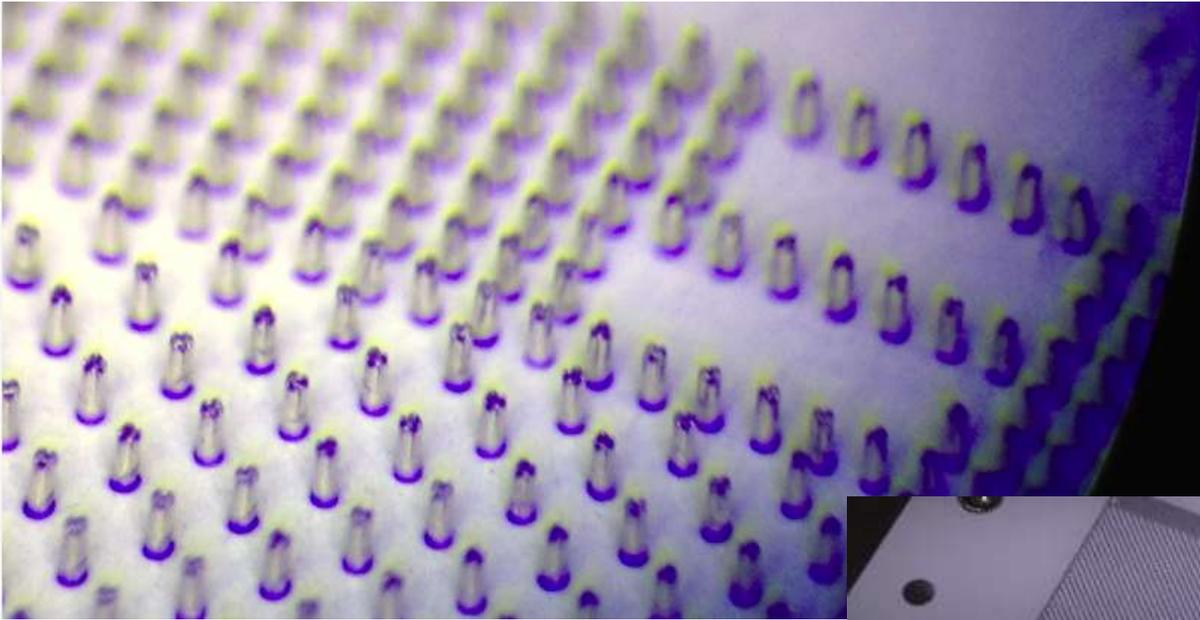
2024

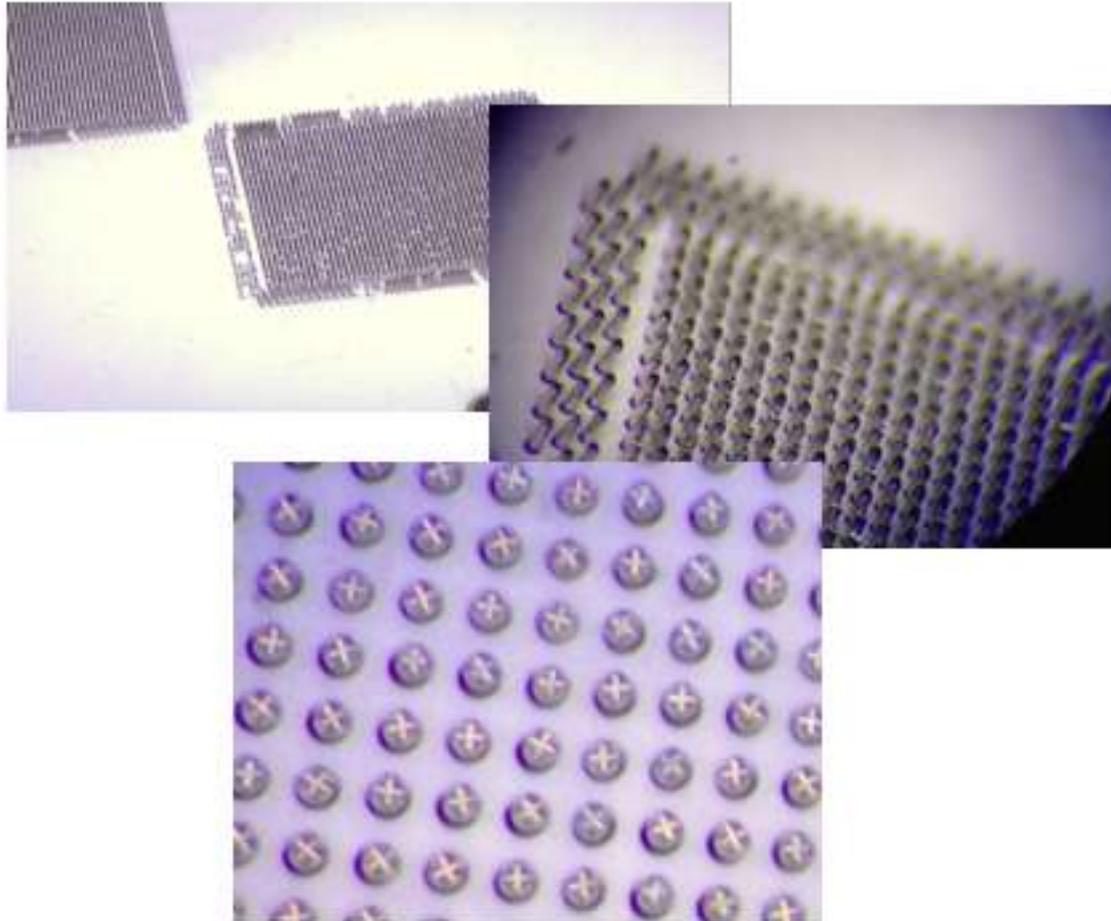


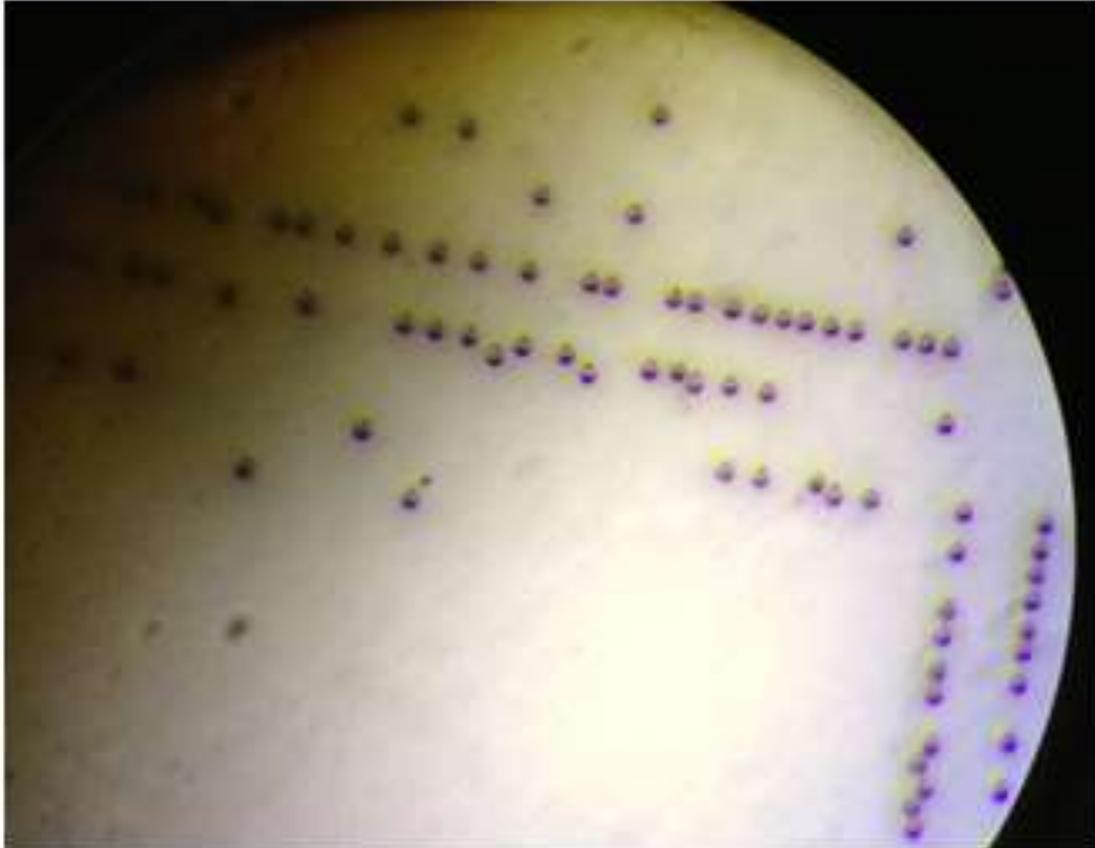
Contactless Inspection for Beam clearance and planarity inspection

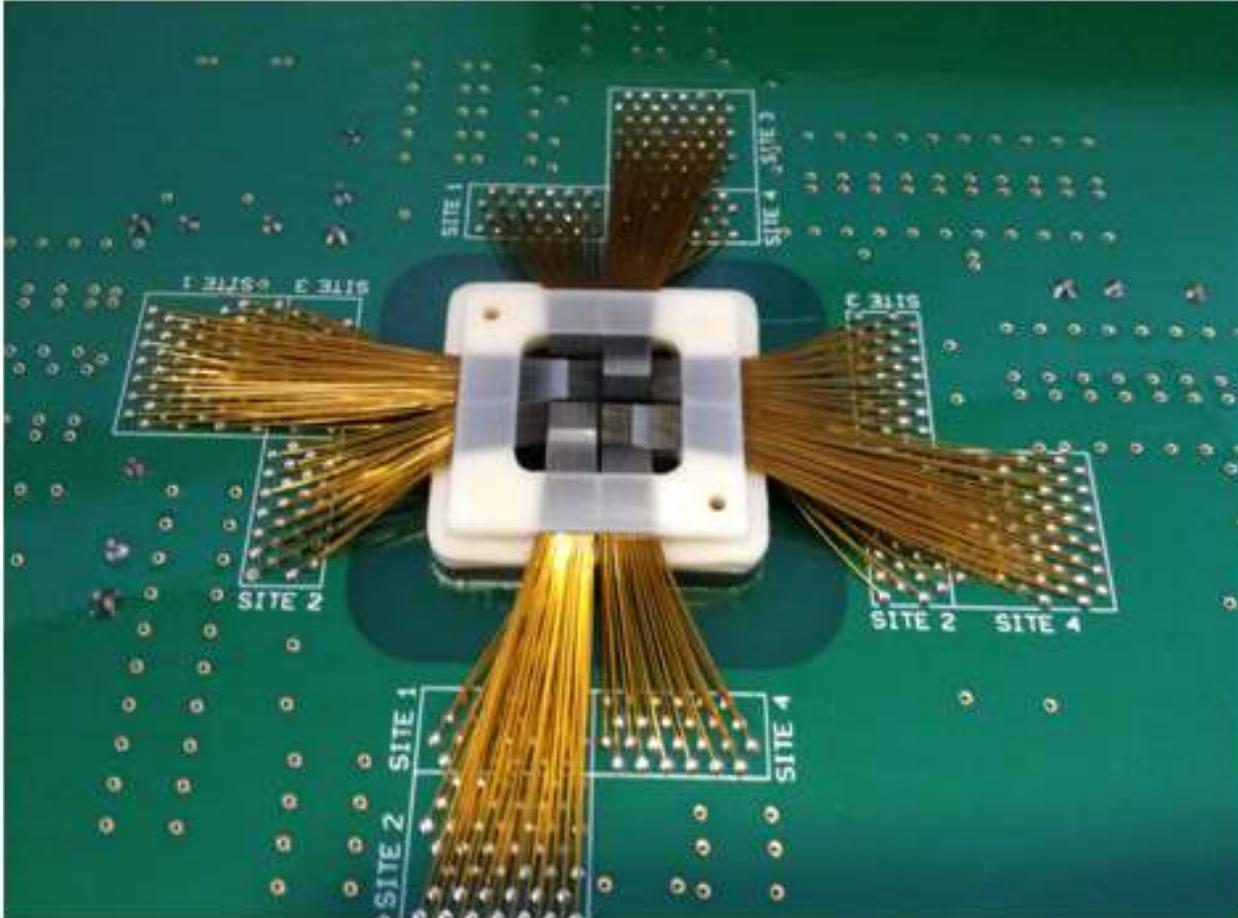
Samples we tested on the inspector

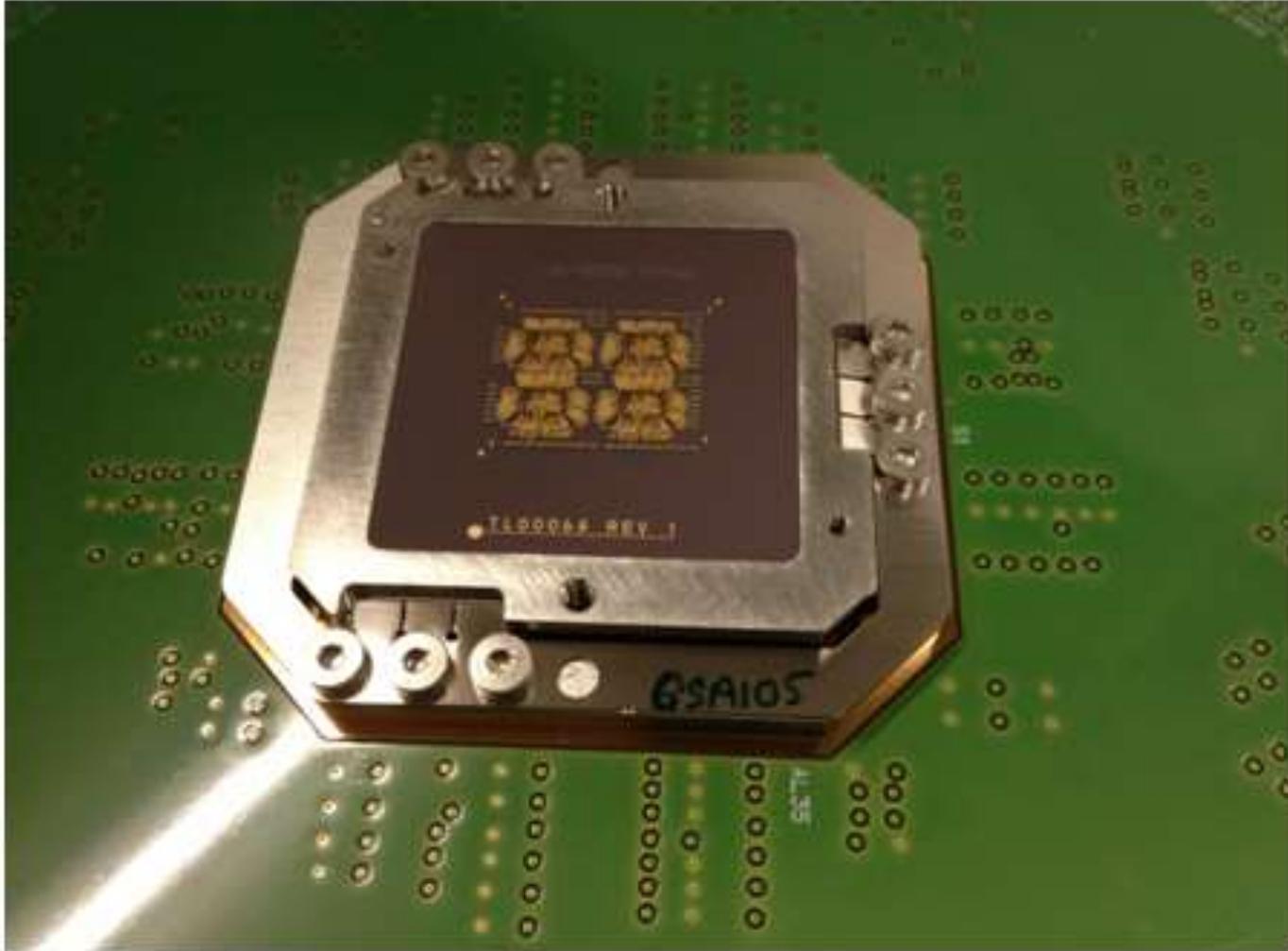
- 2 crown probes
- 1 mems
- 1 cantilever
- 1 vertical 6 micron pin



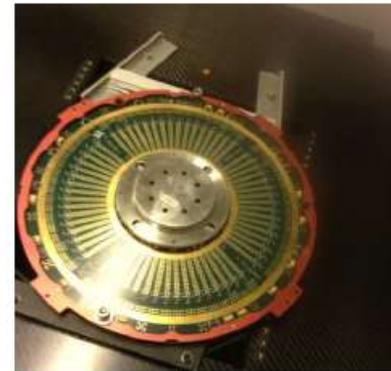
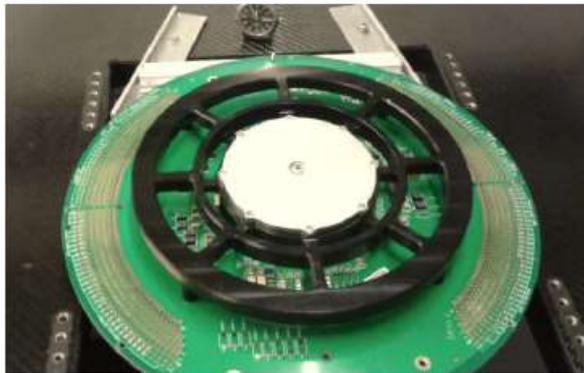
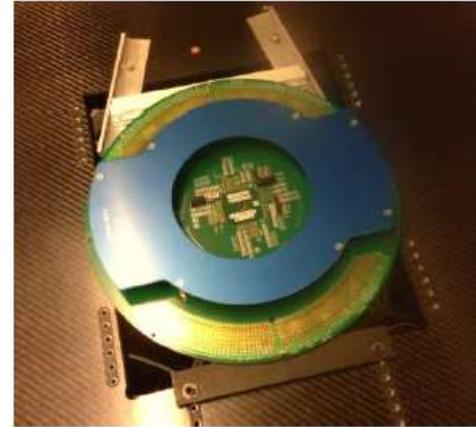
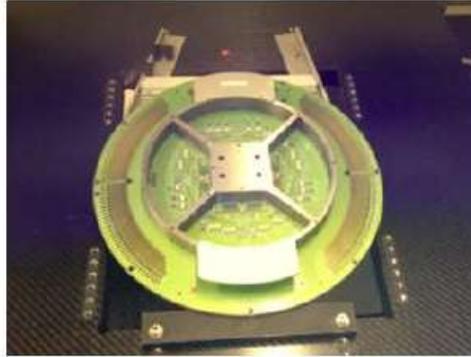
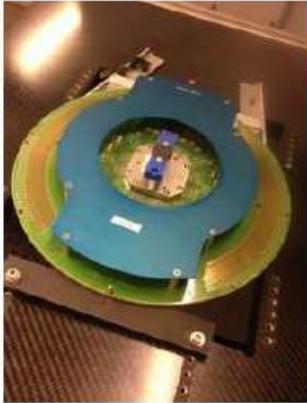




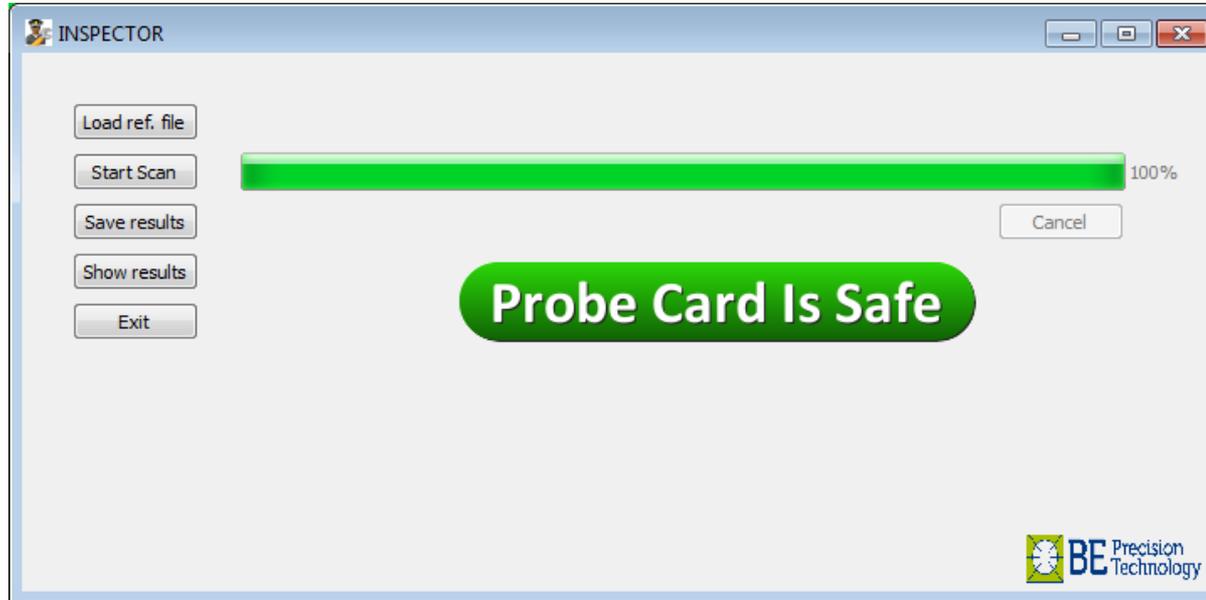




6. Card setup in system



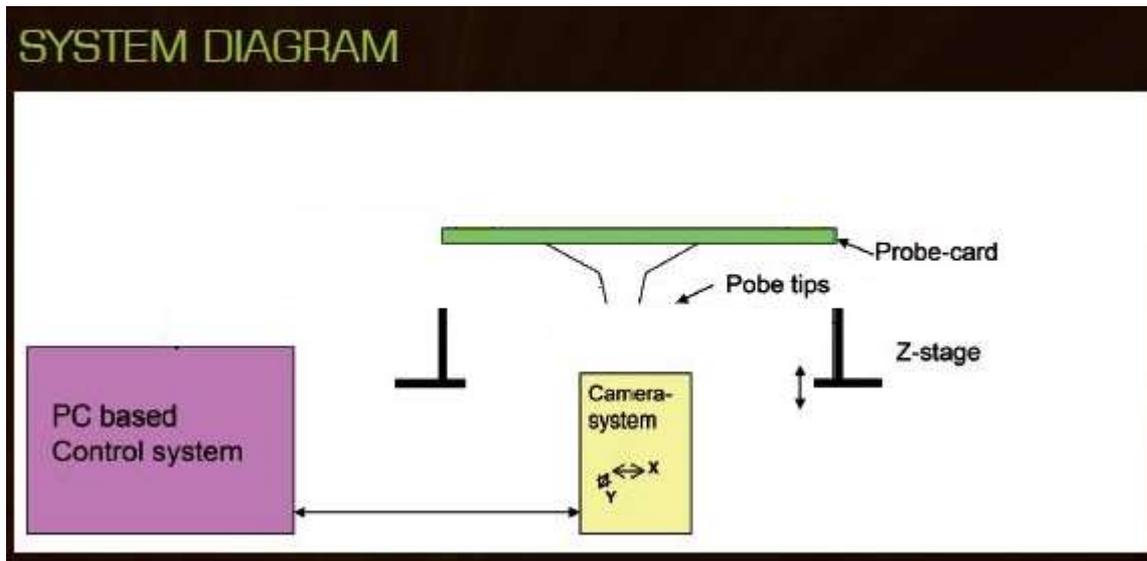
7. Software settings



- Color information for the operator
- Warning for *parts sticking out* over the amount of probes on the card
- Data storing for reference
- Conclusion measurement: this probe card is safe / not safe
- Leveling probe card
- Other data from probe card possible on request

8. System

- System operates explained as below

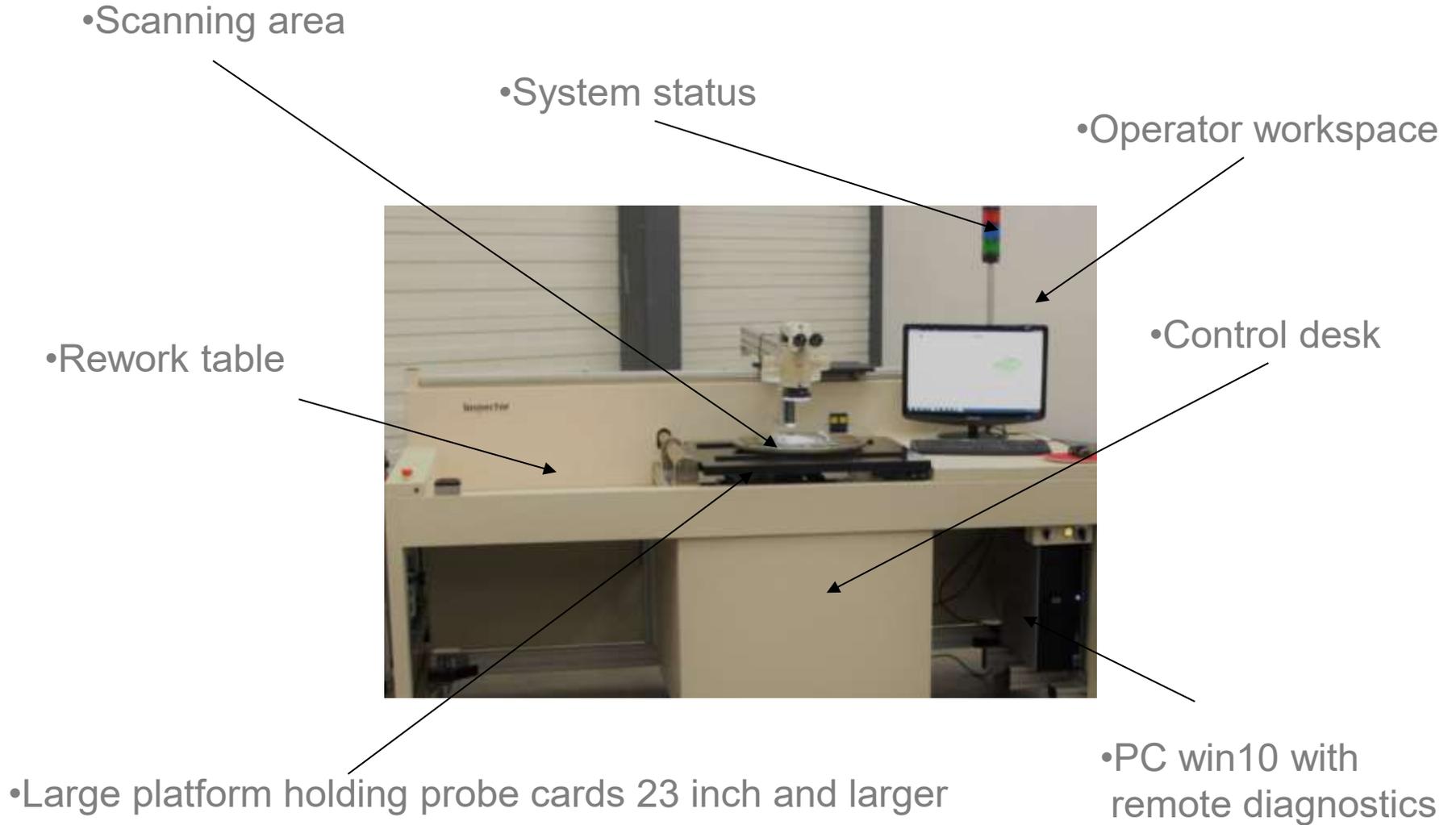


8. System

- System overview



8. System overview



9. Ref file

- Test file is compatible with VX3/4 or M3/5
- System uses this data for analyses
- Add features to the STD ref file
- Few settings; only 1 time setup for each *family* type

```
Units:      MIXED
4,0000 Elec OT          4,0000 Vision OT          5,0000 Max OT
0,5000 Planarity (max. Z dev +/-)          Planarity: Median
0,7000 Elec Align (max. X,Y dev +/-)
0,7000 Vision Align (max. X,Y dev +/-)
2,2 Probe spring rate (grams/unit)
2,0 Probe Force (max. grams dev +/-)
390,0000 Specified probe depth          0,0000 Actual probe depth

Test fixture -
No.:      PP4400      Height:      535,0000
Save      100 tests before deleting

Extended Header:  INSPECTOR:beamclearance=150
Extended Header:  INSPECTOR:Probetype=vertical
EXTENDED HEADER:ADD 150 MILS SHIM
EXTENDED HEADER:DEPOP- SITE 2 ONLY(785 PROBES)
EXTENDED HEADER:DEF1=1, 3, 4, 13, 19, 44, 47, 48, 65, 71, 112, 114, 118, 119, 123, 126, 128, 130, 147, 169, 171, 175, 176, 194, 209, 239, 260, 307, 312, 313, 314;
```

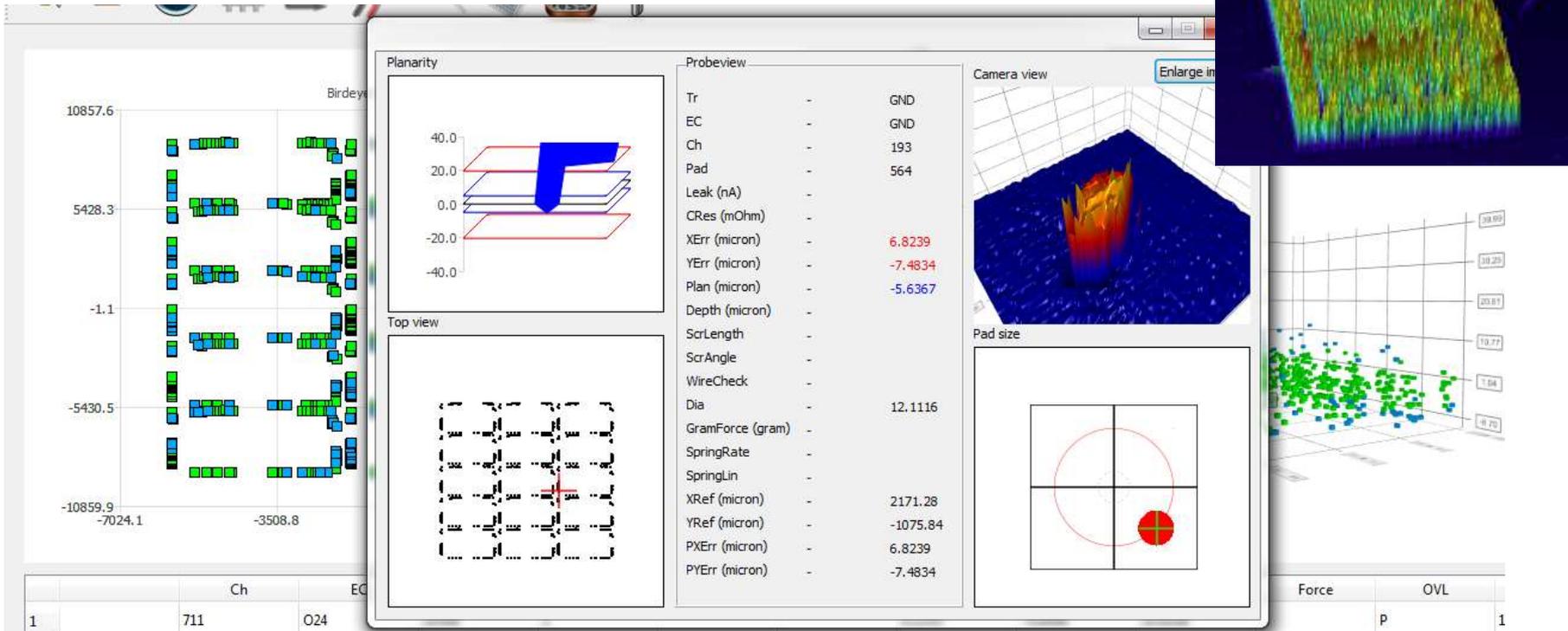
9. Pass / Failure analyses

- System warning for sticking out parts over probes on the card.
- Software shows *free zone* level from lowest tip to higher fixture up to 200 / 400 Micron.
- Software shows result *free zone* to operator.
- Safety level is programmed in ref file.



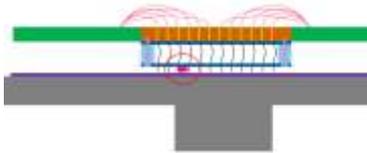
10. Advantages

- See beam clearance at ones, broken head etc
- Maximize the life time of the probecard, no worrie on beam length.
- Detect particals on probecard thats can damage wafer
- Wafer quality improvement
- 2 D and 3 D information in 1 test

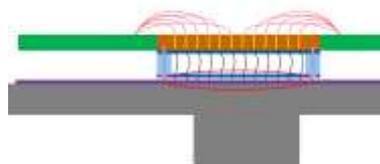


10. Advantages

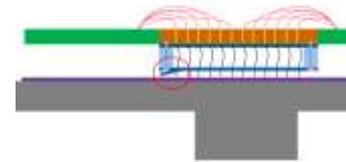
Imprint Risk #1: Particle



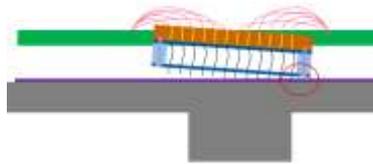
Imprint Risk #2: Short Needles



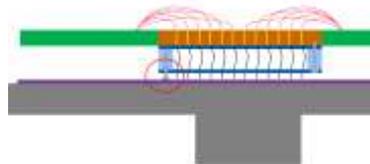
Imprint Risk #3: Broken Ceramic



Imprint Risk #4: Tilted Probe Head

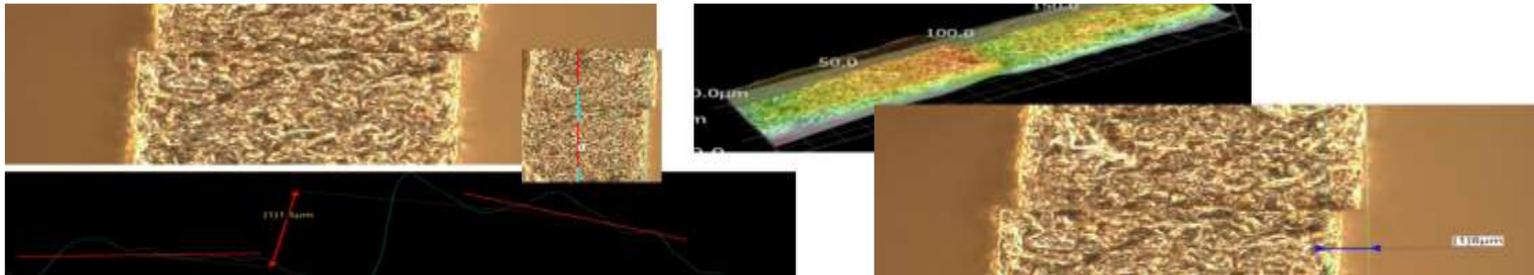


Imprint Risk #5: Loosened Screws



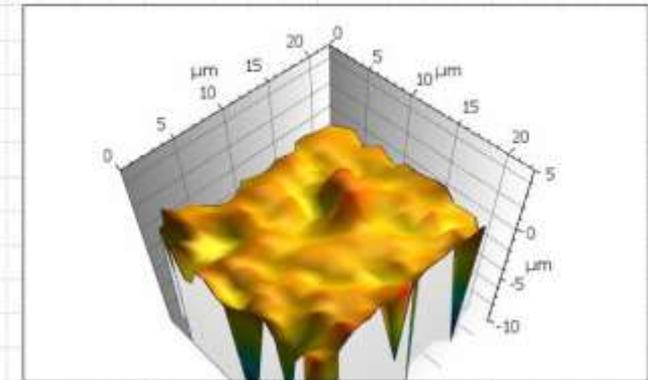
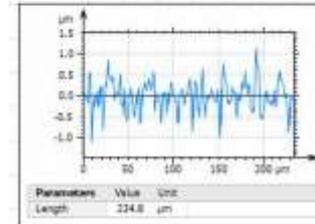
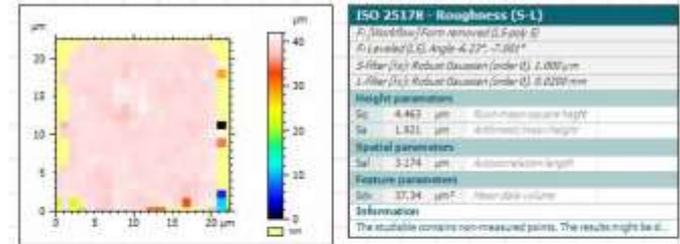
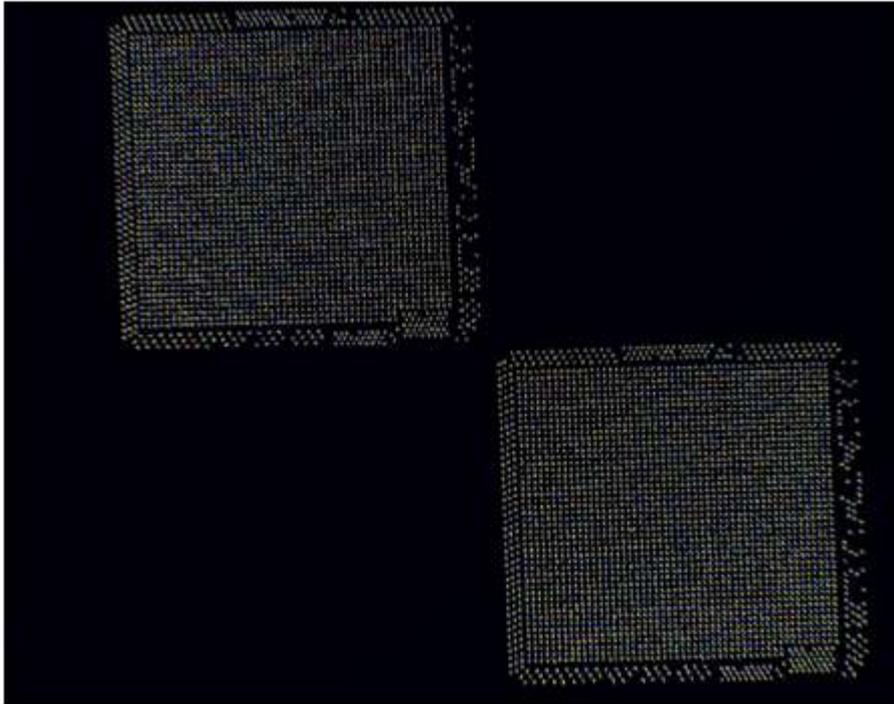
Potential Risks causing Wafer Imprints

- Loose particle on probe head or wafer
- Tip wear out
- Broken ceramic / epoxy-ring
- Tilted probe head
- Tilted probe head plate
- Loosened screws
- High overdrive
- Wafer bow
- ...



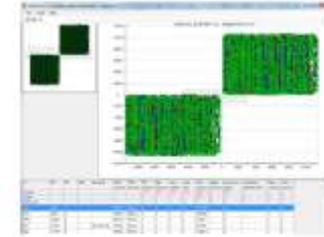
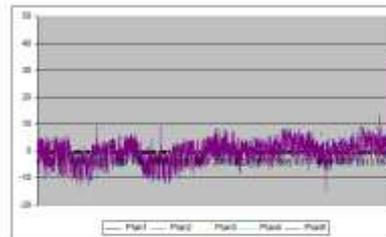
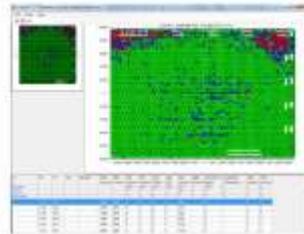
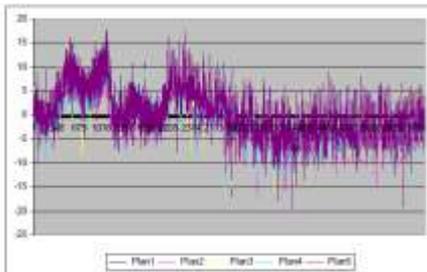
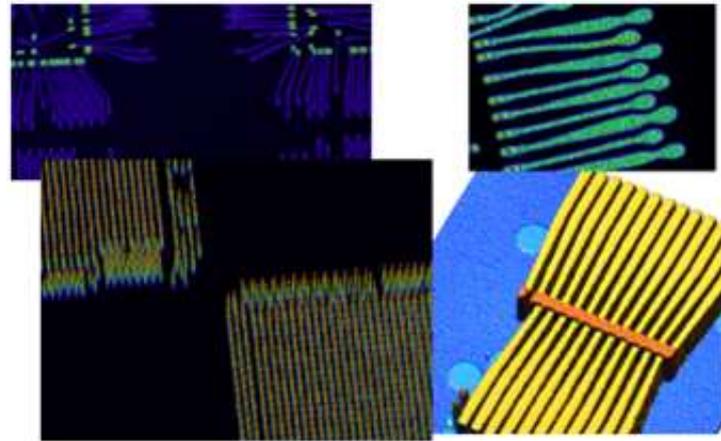
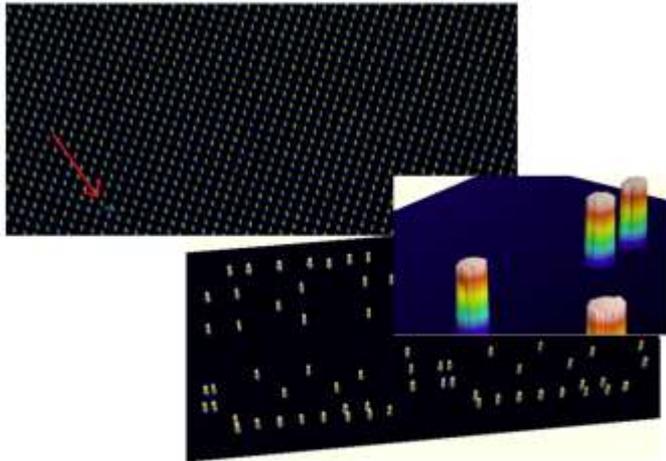
- Inspector cares for all these issues and controls the Yield of the probecard
- Even haircracks in probes are now measured and warned to the operator

10. Advantages



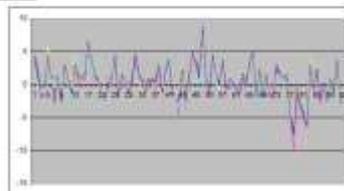
- Maximum details not just XYZ but full head inspection
- Maximize the life time of the probecard, dust parts poluting the wafer
- Detect particals on probecard thats can damage wafer
- Probe tip roughness measurement, is the probe sliding over the pad or collecting materials?

10. Advantages



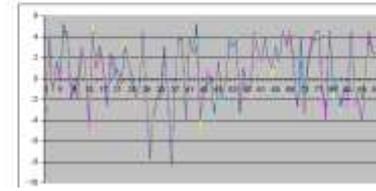
•The cards were measured 5 times to see the repeatability of the system

•Bottom picture is the zoomout of the first 100 pins



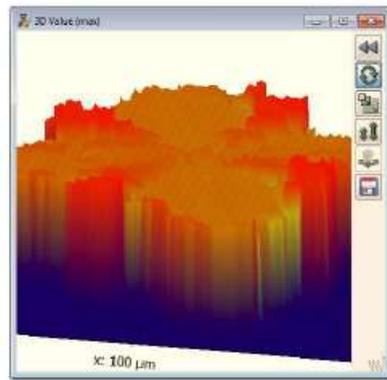
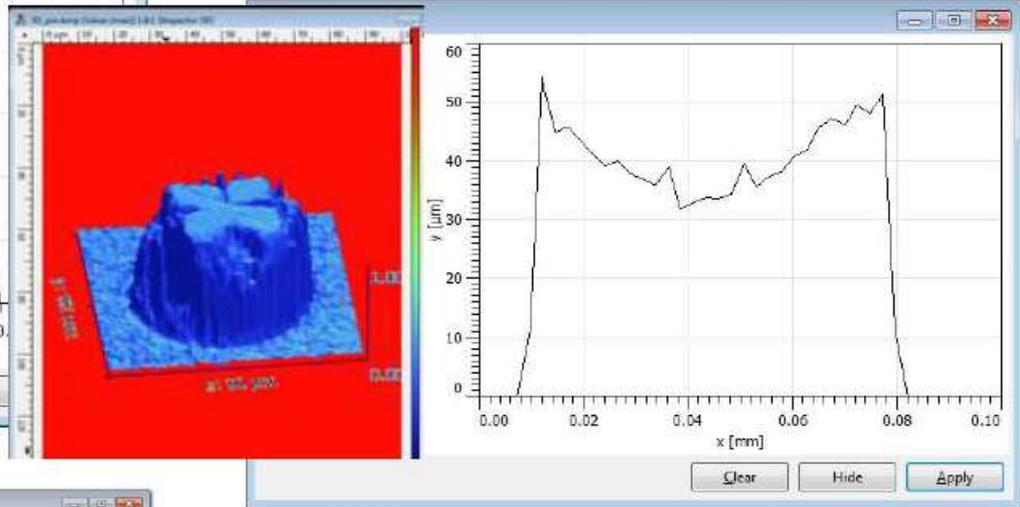
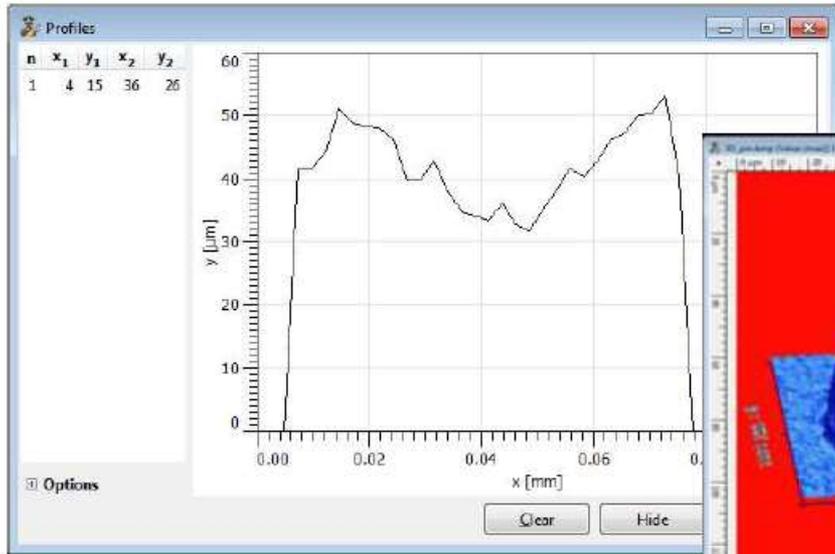
•The cards were measured 5 times to see the repeatability of the system

•Side picture is the zoomed out data of the first 100 probes



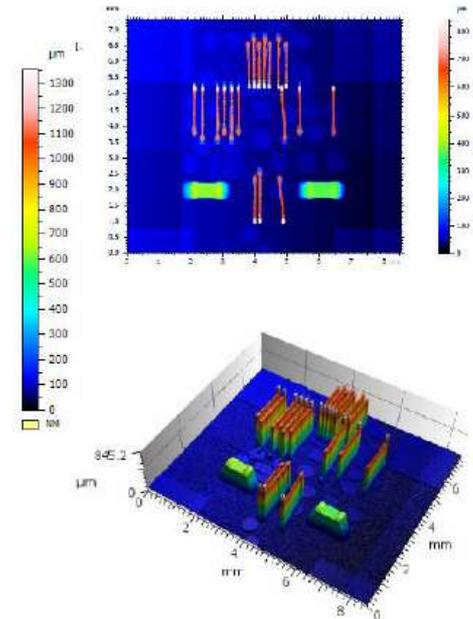
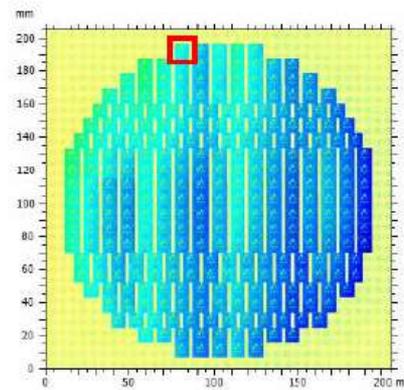
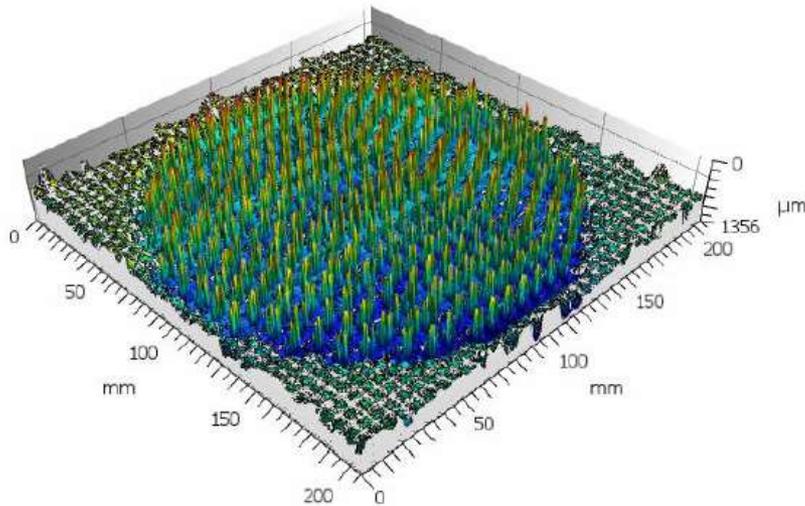
10. Advantages

- The valley depth
- XY pin alignment
- Total alignment error



Pin#	Planarity	Crown Valley	Diameter	X_Err	Y_Err	XY_Err
1	2,56	16,92	77,73	8,68	3,81	9,48
2	1,96	25,02	70,39	8,39	4,47	9,51
3	3,66	18,62	80,28	-5,94	1,64	6,16
4	1,06	23,72	65,19	16,15	15,55	22,42
5	0,86	24,72	72,76	-6,93	6,94	9,8
6	-0,94	32,23	76,57	0,76	4,15	4,22
7	3,16	26,62	66,46	0,41	7,22	7,23
8	2,16	22,92	66,55	2,34	10,06	10,33
9	1,96	25,22	71,56	4,78	-11,98	12,9
10	2,86	22,32	82,9	-0,13	-6,02	6,02

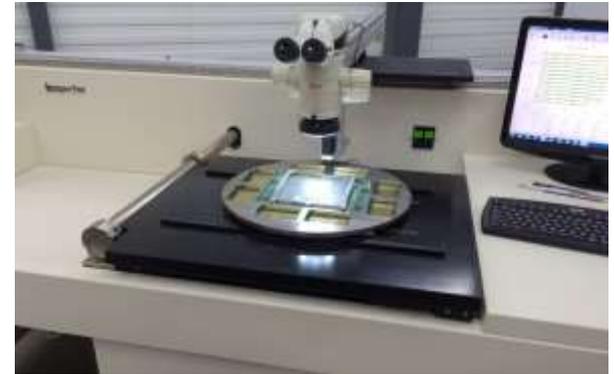
11. Fast scan full probecard Advantages



- Full probecard can be scanned with 1mm deep searching area for full protrusion, XY alignment, planarity and many others parts/ issues.
- Depending of size of the Die / tiles from 5 minutes to 1 hour maximum 300 mm

12 Specifications

- Scanning area 200 mm till 480 mm
- XY resolution from 0.5 to 5 micron
- Z resolution 0.1 micron
- High speed in 5 micron mode
- 80 mm area less then 6 minutes (resolution 5 micron)
- 200 mm probecard 10 minutes full test
- 300 mm probecard 30 minutes full test
- Vertical card sample was scanned in 65 seconds
- Contactless measurement, no investement in expensive fixtures
- Scanning height 400 micron in 1 step, more steps give large depth
- Total Z stage travel 25 mm
- Large probecard can be mounted with large various platforms
- Fully automated process after setup
- Win 11 operating system
- Re-test in higher resolution for detailed diagnostics
- Other features to be discussed, like roughness measurement on tip



Inspector

Contactless Inspection



 info@probecardtester.com

 www.probecardtester.com